L Number	Hits	Search Text	DB	Time stamp
1	1	("5849608").PN.	USPAT	2004/11/05 18:36
2	28	polyimide near (encapsulant or encapsulate)	USPAT	2004/11/05 18:36
3	34	polyimide near (encapsulant or encapsulate)	USPAT; EPO; JPO;	2004/11/05 18:37
4	21	(polyimide near (encapsulant or	DERWENT; IBM_TDB USPAT;	2004/11/05
		encapsulate)) and (@ad<19970804)	EPO; JPO; DERWENT; IBM TDB	18:42
5	160	257/666.ccls. and (@ad<19970804) and (encapsualnt or encapsulate or resin or silicone or mold or molding) and (ball or bump or balls)	USPAT; EPO; JPO; DERWENT; IBM TDB	2004/11/05 18:43
6	165	257/666.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding) and (ball or	USPAT; EPO; JPO; DERWENT;	2004/11/05 18:45
7	175	bump or balls) 257/666.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic)	IBM_TDB USPAT; EPO; JPO; DERWENT;	2004/11/05 19:25
8	17	and (ball or bump or balls) 5849608.URPN.	IBM_TDB USPAT	2004/11/05
9	1	("5849608")PN.	USPAT	2004/11/05 18:57
10	98	257/666.ccls. and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic)	USPAT; EPO; JPO; DERWENT;	2004/11/05 19:26
11	12491	and (ball or bump or balls) (chip or die) and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls)	IBM_TDB USPAT; EPO; JPO; DERWENT; IBM TDB	2004/11/05 19:22
12	5222	((chip or die) and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls)) and (lead or	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:23
13	1969	leads) ((chip or die) and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls)) and ((lead or leads) with ((chip or die) or (ball or	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:24
14	30778	bump or balls or bumps))) (((chip or die) and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic)	USPAT; EPO; JPO; DERWENT;	2004/11/05 19:24
	·	and (ball or bump or balls)) and ((lead or leads) with ((chip or die) or (ball or bump or balls or bumps))) nt (257/666.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls))	IBM_TDB	
15	1885	(((chip or die) and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls)) and ((lead or leads) with ((chip or die) or (ball or bump or balls or bumps))) not (257/666.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls))	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:24

	1010	1 (-bin	Transm.	12004/11/05
16	1219	((chip or die) and (@ad<19950508) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls)) and ((lead or leads) with (ball or bump or balls or	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05
17	1163	(encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls)) and ((lead or leads) with (ball or bump or balls or bumps))) not (257/666.ccls. and (@ad<19970804) and (encapsulant or	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:26
	150	encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls))		
18	156	257/738.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (lead or leads)	USPAT; EPO; JPO; DERWENT; IBM TDB	2004/11/05
19	142		USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:35
20	52	((257/738.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (lead or leads)) not (257/666.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (ball or bump or balls))) and (@ad<19950508)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05
21	1969		USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/05 19:30
22	102	257/734.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (lead or leads)	USPAT; EPO; JPO; DERWENT; IBM TDB	2004/11/05
23	85	(257/734.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (lead or leads)) and (@ad<19950508)	USPAT; EPO; JPO; DERWENT; IBM TDB	2004/11/05 19:30
24	128	257/780.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic) and (lead or leads)	USPAT; EPO; JPO; DERWENT; IBM TDB	2004/11/05
25	59	(257/780.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic)	USPĀT; EPO; JPO; DERWENT;	2004/11/05 19:31
26	193	and (lead or leads)) and (@ad<19950508) 257/737.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic)	IBM_TDB USPAT; EPO; JPO; DERWENT;	2004/11/05 19:31
27	87	and (lead or leads) (257/737.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic)	IBM_TDB USPAT; EPO; JPO; DERWENT;	2004/11/05 19:31
28	63	and (lead or leads)) and (@ad<19950508) 438/612.ccls. and (@ad<19970804) and (encapsulant or encapsulate or resin or silicone or mold or molding or plastic)	IBM_TDB USPAT; EPO; JPO; DERWENT;	2004/11/05 19:33
		and (lead or leads)	IBM_TDB	

29	35	(438/612.ccls. and (@ad<19970804) and	USPAT;	2004/11/05
		(encapsulant or encapsulate or resin or	EPO; JPO;	19:32
		silicone or mold or molding or plastic)	DERWENT;	
		and (lead or leads)) and (@ad<19950508)	IBM TDB	
30	122	438/123.ccls. and (@ad<19970804) and	USPAT;	2004/11/05
		(encapsulant or encapsulate or resin or	EPO; JPO;	19:33
		silicone or mold or molding or plastic)	DERWENT;	
		and (ball or bump or balls or bumps)	IBM TDB	
31	66	438/123.ccls. and (@ad<19950508) and	USPAT;	2004/11/05
31		(encapsulant or encapsulate or resin or	EPO; JPO;	19:35
		silicone or mold or molding or plastic)	DERWENT;	13.33
		and (ball or bump or balls or bumps)	IBM TDB	
32	31	438/124.ccls. and (@ad<19950508) and	USPAT;	2004/11/05
34	31	(encapsulant or encapsulate or resin or	EPO; JPO;	19:36
		silicone or mold or molding or plastic)	DERWENT;	19:36
		and (ball or bump or balls or bumps)	IBM TDB	
33	21	(438/124.ccls. and (@ad<19950508) and	USPAT;	2004/11/05
33	21		EPO; JPO;	19:36
		(encapsulant or encapsulate or resin or		19:36
		silicone or mold or molding or plastic)	DERWENT;	
		and (ball or bump or balls or bumps)) not	IBM_TDB	
		(438/123.ccls. and (@ad<19950508) and		
		(encapsulant or encapsulate or resin or		!
		silicone or mold or molding or plastic)		•
		and (ball or bump or balls or bumps))		
34	40	438/15.ccls. and (@ad<19950508) and	USPAT;	2004/11/05
		(encapsulant or encapsulate or resin or	EPO; JPO;	19:37
		silicone or mold or molding or plastic)	DERWENT;	
		and (ball or bump or balls or bumps)	IBM_TDB	
35	3	438/22.ccls. and (@ad<19950508) and	USPAT;	2004/11/05
		(encapsulant or encapsulate or resin or	EPO; JPO;	19:38
		silicone or mold or molding or plastic)	DERWENT;	
		and (ball or bump or balls or bumps)	IBM_TDB	
36	18	438/122.ccls. and (@ad<19950508) and	USPAT;	2004/11/05
		(encapsulant or encapsulate or resin or	EPO; JPO;	19:42
		silicone or mold or molding or plastic)	DERWENT;	
		and (ball or bump or balls or bumps)	IBM_TDB	
37	14	438/111.ccls. and (@ad<19950508) and	USPAT;	2004/11/05
		(encapsulant or encapsulate or resin or	EPO; JPO;	19:42
		silicone or mold or molding or plastic)	DERWENT;	
		and (ball or bump or balls or bumps)	IBM TDB	